

MECHANICAL CASE OUTLINE

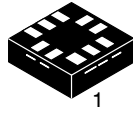
PACKAGE DIMENSIONS

ON Semiconductor®

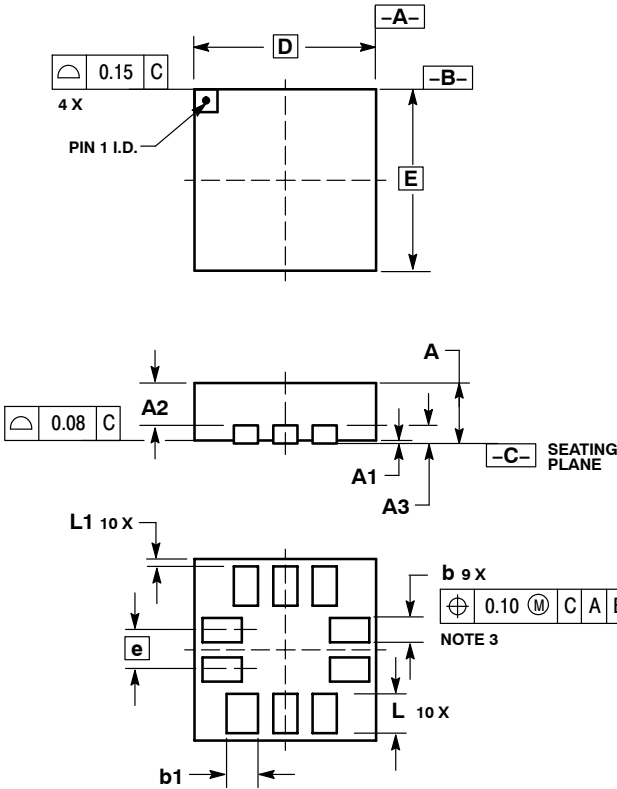


10 PIN QFN, 3x3 CASE 501-02 ISSUE B

DATE 11/20/2002



SCALE 4:1

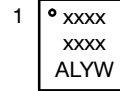


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINALS AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. 501-01 OBSOLETE, NEW STANDARD IS -02.

MILLIMETERS		
DIM	MIN	MAX
A	0.800	1.000
A1	0.000	0.050
A2	0.600	0.800
A3	0.203	REF
D	3.00	BSC
E	3.00	BSC
b	0.371	0.421
b1	0.498	0.548
e	0.650	BSC
L	0.523	0.673
L1	0.000	0.127

MARKING DIAGRAM



- xxxx = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week

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